

Title (en)

Embedded chip packages and methods for manufacturing an embedded chip package

Title (de)

Eingebettete Chipgehäuse und Verfahren zur Herstellung eines eingebetteten Chipgehäuses

Title (fr)

Boîtiers de puce intégré et procédés de fabrication d'un tel boîtier

Publication

**EP 2722876 A2 20140423 (EN)**

Application

**EP 13189068 A 20131017**

Priority

- EP 12007249 A 20121019
- US 201313736097 A 20130108
- EP 13189068 A 20131017

Abstract (en)

A method for manufacturing an embedded chip package is provided. The method may include: forming electrically conductive lines (312) over a substrate (314); placing the substrate next to a chip arrangement comprising a chip (326), the chip comprising one or more contact pads (328), wherein one or more of the electrically conductive lines are arranged proximate to a side wall (332) of the chip; and forming one or more electrical interconnects (342) over the chip arrangement to electrically connect at least one electrically conductive line (312) to at least one contact pad (328).

IPC 8 full level

**H01L 23/538** (2006.01)

CPC (source: EP)

**H01L 23/5389** (2013.01); **H01L 24/24** (2013.01); **H01L 24/82** (2013.01); **H01L 24/96** (2013.01); **H01L 24/97** (2013.01); **H01Q 1/2283** (2013.01); **H01L 23/3128** (2013.01); **H01L 23/49816** (2013.01); **H01L 23/5384** (2013.01); **H01L 23/66** (2013.01); **H01L 24/16** (2013.01); **H01L 24/32** (2013.01); **H01L 24/48** (2013.01); **H01L 24/73** (2013.01); **H01L 25/105** (2013.01); **H01L 25/16** (2013.01); **H01L 2223/6627** (2013.01); **H01L 2223/6677** (2013.01); **H01L 2223/6683** (2013.01); **H01L 2224/0401** (2013.01); **H01L 2224/04105** (2013.01); **H01L 2224/12105** (2013.01); **H01L 2224/16225** (2013.01); **H01L 2224/24195** (2013.01); **H01L 2224/32145** (2013.01); **H01L 2224/32245** (2013.01); **H01L 2224/48227** (2013.01); **H01L 2224/73267** (2013.01); **H01L 2224/97** (2013.01); **H01L 2225/06562** (2013.01); **H01L 2225/1035** (2013.01); **H01L 2225/1041** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/12042** (2013.01); **H01L 2924/1423** (2013.01); **H01L 2924/1431** (2013.01); **H01L 2924/1434** (2013.01); **H01L 2924/1461** (2013.01); **H01L 2924/15311** (2013.01); **H01L 2924/181** (2013.01); **H01L 2924/19041** (2013.01); **H01L 2924/19042** (2013.01); **H01L 2924/19043** (2013.01); **H01L 2924/19105** (2013.01)

Cited by

DE102015121044A1; DE102015121044B4; US10217695B2; WO2016100267A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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**EP 2722876 A2 20140423**; **EP 2722876 A3 20160427**; EP 3444840 A2 20190220; EP 3444840 A3 20190508

DOCDB simple family (application)

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